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ASSIGNMENT RECORDATION COVER SHEET
-PATENTS ONLY-

JCS30 U.S. PTO
09/304436
05/03/99

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)
 - a) Chih-Chien Liu
 - b) Kun-Chih Wang
 - c) Wen-Yi Hsieh
 - d) Yimin Huan

2. Name and address of receiving party(ies):
 - a) Name: United Microelectronics Corp.
 - Address: No. 3, Li-Hsin Rd. II
Science-Based Industrial Park
Hsinchu, Taiwan
R.O.C.

3. Nature of conveyance

<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name
<input type="checkbox"/> Other _____	<input type="checkbox"/> License Agreement

Execution Date: April 19, 1999

4. Application Number(s) or Patent Number(s): Not yet assigned **09/304436**

The title of the (new) application is:

METHOD OF METHOD OF FABRICATING A COPPER CAPPING LAYER

5. Please send all correspondence concerning this (these) documents to:

HICKMAN STEPHENS & COLEMAN, LLP
P.O. Box 52037
Palo Alto, CA 94303-0746
Tel. No.: (650) 470-7430
Fax No.: (650) 470-7440

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- | | |
|-------------------------------------|--|
| <input checked="" type="checkbox"/> | Enclosed |
| <input type="checkbox"/> | Authorized to be charged to Deposit Account No. 50-0384
(Order No. _____) |

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8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: May 3, 1999

[Signature]

L. Keith Stephens
Registration No. 32,632

ASSIGNMENT

WHEREAS,

1. Chih-Chien Liu
3. Wen-Yi Hsieh

2. Kun-Chih Wang
4. Yimin Huang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD OF FABRICATING A COPPER CAPPING LAYER**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Chih-Chien Liu

Signature:

Sole or First Joint Inventor: Chih-Chien Liu

Apr. 19, 1999

Date:

Kun-Chih Wang

Signature:

Second Joint Inventor (if any): Kun-Chih Wang

Apr. 19, 1999

Date:

Wen-Yi Hsieh

Signature:

Third Joint Inventor (if any): Wen-Yi Hsieh

Apr. 19, 1999.

Date:

Yimin Huang

Signature:

Fourth Joint Inventor (if any): Yimin Huang

Apr. 19, 1999

Date: